


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/21/12542	
1.3 Title of PCN	AMKOR ATP (Philippines) enhanced Die Attach - All listed product in UFBGA package	
1.4 Product Category	All products in UFBGA 5x5, UFBGA 7x7 or UFBGA 10x10 packages	
1.5 Issue date	2021-02-23	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	GAMERL ANN
2.1.2 Phone	
2.1.3 Email	ann.gamerl@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Die Attach material	AMKOR ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Die Attach Film (DAF) material: Henkel ATB-130U	Die Attach Film (DAF) material: Nitto EM760L2-P
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	improve Die Attach fillet height condition
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Tracability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2021-02-10
7.2 Intended start of delivery	2021-04-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12542 MDG-MCD-RER2020 V1.0-PCN12542-AMKOR ATP enhanced Die Attach UFBGA.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-02-23

9. Attachments (additional documentations)

12542 Public product.pdf
12542 MDG-MCD-RER2020 V1.0-PCN12542-AMKOR ATP enhanced Die Attach UFBGA.pdf
12542 PCN12542_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F407IGH6	
	STM32H753IIK6	

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